

METHOD AND SYSTEM FOR CLEANING A SEMICONDUCTOR WAFER

ABSTRACT OF THE DISCLOSURE

A method and a system are provided for cleaning a surface of a wafer. The
5 method starts by scrubbing the surface of the wafer with a cleaning brush that applies a
chemical solution to the surface of the wafer. In one example, the cleaning brush
implements a through the brush (TTB) technique to apply the chemicals. The scrubbing
is generally performed in a brush box, with a top cleaning brush and a bottom cleaning
brush. The top cleaning brush is then removed from contact with the surface of the wafer.
10 The chemical concentration in the top brush may be maintained at substantially the same
concentration that was in the brush during the scrubbing operation. Next, a flow of water
(preferably de-ionized water) is delivered to the surface of the wafer. The delivery of
water is preferably configured to remove substantially all of the chemical solution from
the surface of the wafer before proceeding to a next cleaning operation.